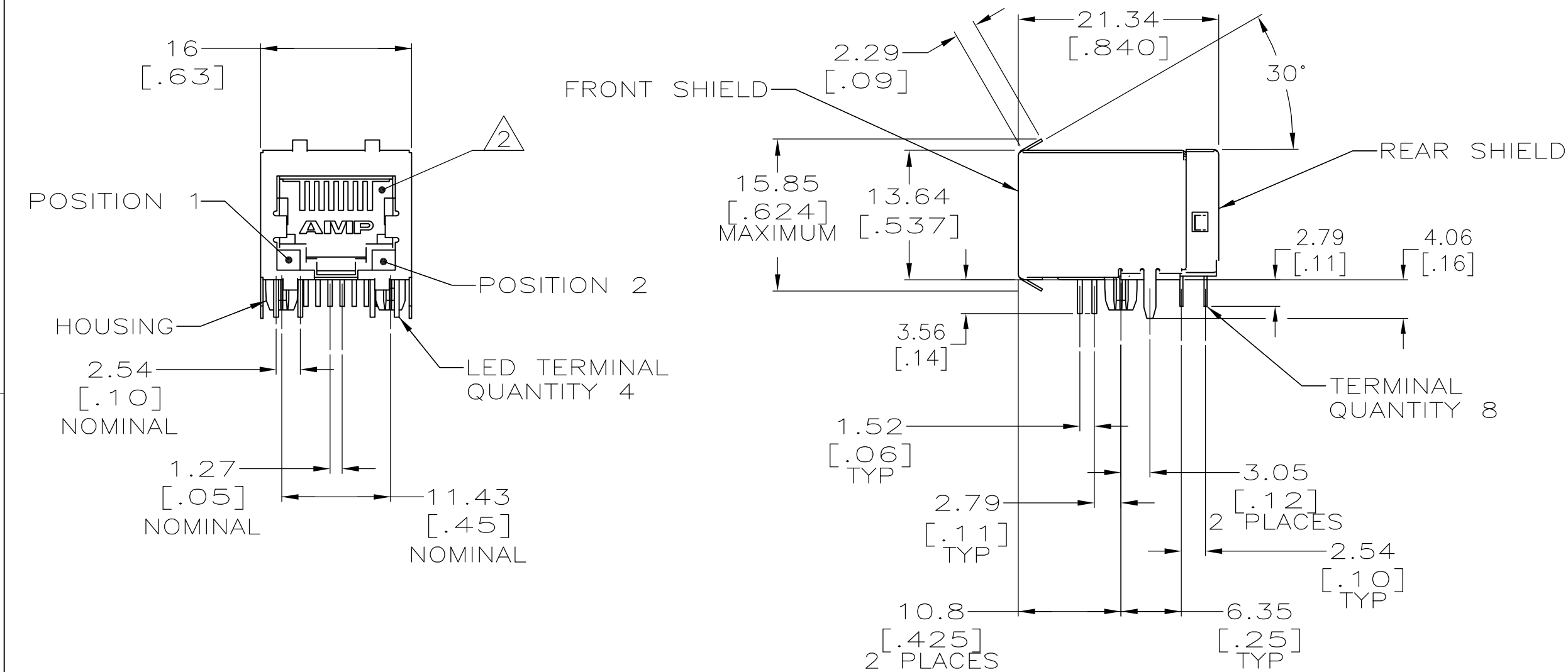
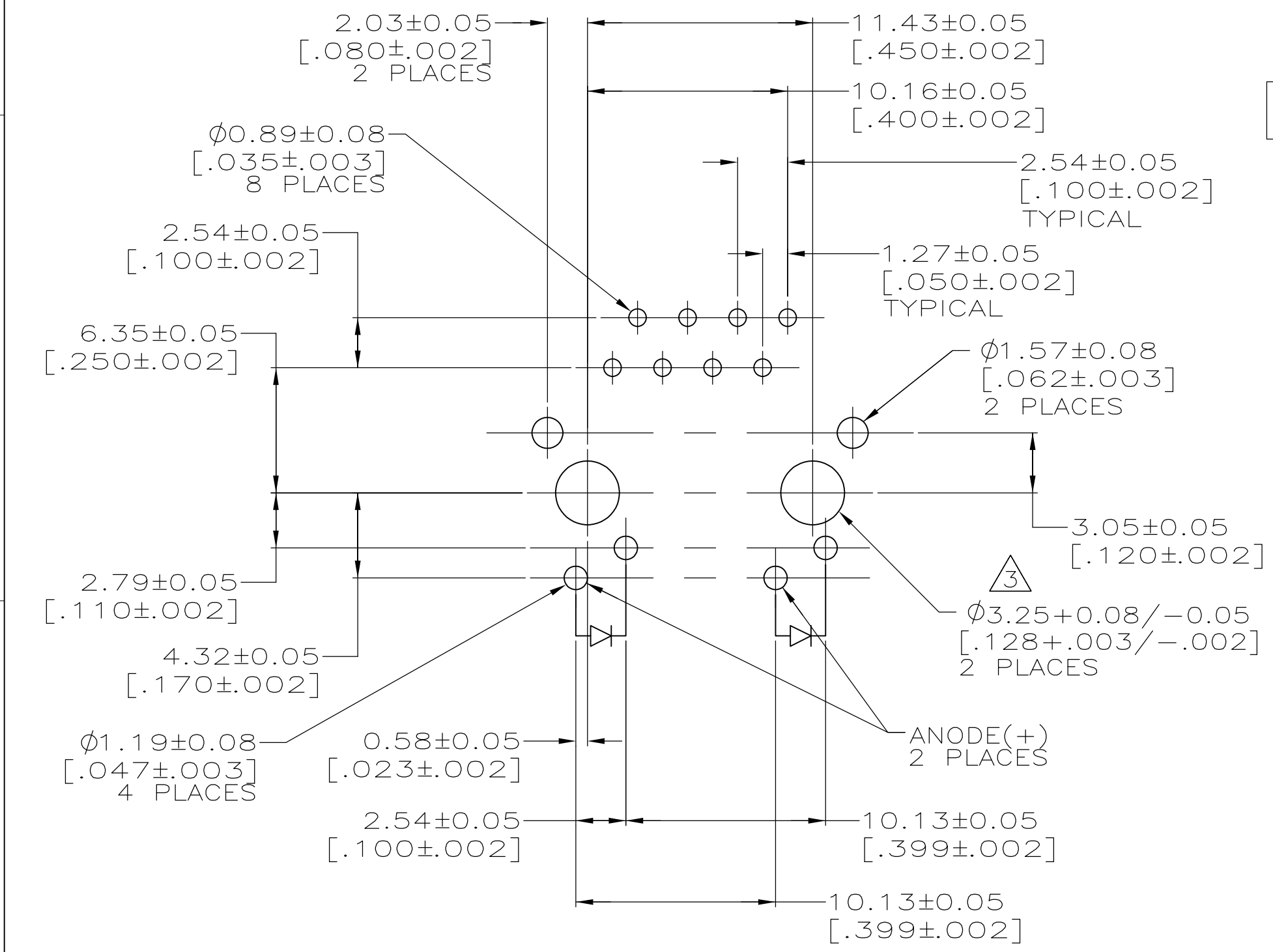
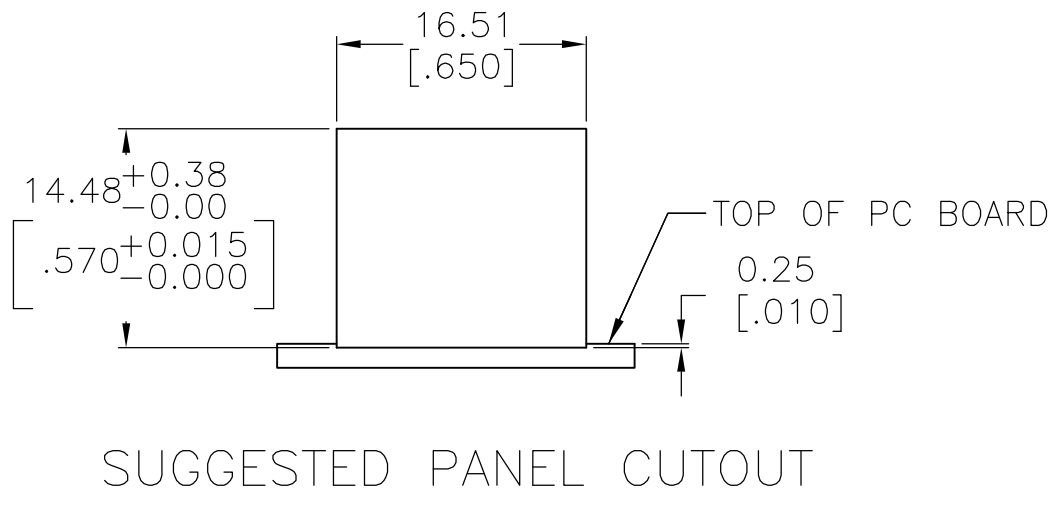


LOC	DIST	REVISIONS					
		P	LTR	DESCRIPTION	DATE	DWN	APVD
AA	00		E2	REVISED PER ECO-11-005033	26MAR11	RK	HMR



- MATERIAL: HOUSING – PBT THERMOPLASTIC BLACK, UL94V-0.
TERMINALS – 0.33[.013] THICK PHOS BRONZE PLATED WITH 1.27 μ m[.000050] MINIMUM THICK HARD GOLD IN LOCALIZED AREA AND 3.81 μ m[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27 μ m[.000050] MINIMUM THICK NICKEL UNDERPLATE.
SHIELDS – 0.25 [.010] THICK COPPER ALLOY PLATED WITH 1.27 μ m[.000050] MINIMUM NICKEL AND 2.03 μ m[.000080] MINIMUM HOT TIN DIP ON PCB GROUND TABS.

LIGHT EMITTING DIODE (LED) – DIFFUSED EPOXY LENS, 0.51 x 0.51[.020 x .020] CARBON STEEL WIREFRAME LEADS PREPLATED WITH 8.89 μ m[.0003500] THICK Sn/Cu OVER 2.03 μ m[.000080] THICK Ag OVER 1.02 μ m[.000040] THICK Cu OVER 3.56 μ m[.000140] THICK Ni OVER 1.02 μ m[.000040] Cu UNDERPLATE
- JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68 SUBPART F.
- USE #30 DRILL BIT OR 3.25mm DRILL BIT WHEN PRODUCING THESE PCB HOLES.
- THIS MODULAR JACK WITH INTEGRATED LEDS IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.



SUGGESTED PC BOARD LAYOUT
COMPONENT SIDE
SCALE 4:1

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN L. VARELA - 07JUN2005	TE Connectivity MODULAR JACK ASSEMBLY, 8 POSITION, RIGHT ANGLE, LOW PROFILE, PANEL GROUND WITH LEDS			
DIMENSIONS: mm [INCHES]		CHK J. WESTMAN 07JUN2005				
	TOLERANCES UNLESS OTHERWISE SPECIFIED:		NAME S. FLICKINGER			
	0 PLC ± -		PRODUCT SPEC 108-1163			
	1 PLC ± -		APPLICATION SPEC 114-2154			
MATERIAL		FINISH	WEIGHT -	SIZE A2	CAGE CODE 00779	DRAWING NO C=5569564
CUSTOMER DRAWING			SCALE 2:1	SHEET 1 of 1	REV E2	